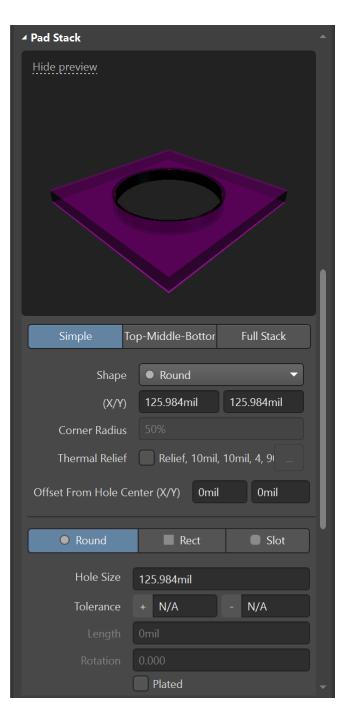
#	Name	Material	Туре	Weight	Thickness	Dk	Df	
	Top Overlay		Overlay					
	Top Solder	Solder Resist	Solder Mask		0.4mil	3.5		
1	Top Layer	<u> </u>	Signal		1.4mil			
	Dielectric 2	PP-006	Prepreg		2.8mil	4.1	0.02	
2	Layer 1	CF-004	Plane	1oz	1.378mil			
	Dielectric 1	FR-4 ···	Dielectric		12.6mil	4.8		
3	Layer 2	CF-004	Plane	1oz	1.378mil			
	Dielectric 3	PP-006	Prepreg		2.8mil	4.1	0.02	
4	Bottom Layer		Signal	1oz	1.4mil			
	Bottom Solder	Solder Resist	Solder Mask		0.4mil	3.5		
	Bottom Overlay		Overlay					

#	Name	Material	Туре	Weight	Thickness	Dk	Df
	Top Overlay		Overlay				
	Top Solder	SM-001	Solder Mask		1mil	4	0.03
	Top Surface Finish	PbSn	Surface Finish		0.787mil		
1	Top Layer	CF-004	Signal	1oz	1.378mil		
	Dielectric 1	PP-017 ···	Prepreg		5.1mil	4.3	0.02
	Dielectric 2	PP-017 ···	Prepreg		5.1mil	4.3	0.02
2	Int1 (GND)	CF-004	Plane	1oz	1.378mil		
	Dielectric 3	Core-039	Core		28mil	4.8	0.02
3	Int2 (PWR)	CF-004	Plane	1oz	1.378mil		
	Dielectric 4	PP-017 ···	Prepreg		5.1mil	4.3	0.02
	Dielectric 5	PP-017 ···	Prepreg		5.1mil	4.3	0.02
4	Bottom Layer	CF-004	Signal	1oz	1.378mil		
	Bottom Surface	PbSn	Surface Finish		0.787mil		
	Bottom Solder	SM-001	Solder Mask		1mil	4	0.03
	Bottom Overlay		Overlay				



Questions:

- ask about routing with ground and power plane with via?
- pad properties
- holes do I need to set the net to anything or do anything?
- Thickness/layer recommendation (1.5 with standard format)
- silk to solder mask clearance (mine is 9.4mil) changed from 10mil to 7.5mil
- hole size constraint (changed from 100mil to 130mil)

